

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2581532

SUBMISSION TYPE:	NEW ASSIGNMENT																		
NATURE OF CONVEYANCE:	ASSIGNMENT																		
CONVEYING PARTY DATA																			
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>HSUN-CHUNG KUANG</td> <td>09/27/2013</td> </tr> <tr> <td>YEN-CHANG CHU</td> <td>10/03/2013</td> </tr> <tr> <td>CHENG-TAI HSIAO</td> <td>09/27/2013</td> </tr> <tr> <td>PING-YIN LIU</td> <td>09/27/2013</td> </tr> <tr> <td>LAN-LIN CHAO</td> <td>09/27/2013</td> </tr> <tr> <td>YEUR-LUEN TU</td> <td>09/27/2013</td> </tr> <tr> <td>CHIA-SHIUNG TSAI</td> <td>09/27/2013</td> </tr> <tr> <td>XIAOMENG CHEN</td> <td>09/27/2013</td> </tr> </tbody> </table>		Name	Execution Date	HSUN-CHUNG KUANG	09/27/2013	YEN-CHANG CHU	10/03/2013	CHENG-TAI HSIAO	09/27/2013	PING-YIN LIU	09/27/2013	LAN-LIN CHAO	09/27/2013	YEUR-LUEN TU	09/27/2013	CHIA-SHIUNG TSAI	09/27/2013	XIAOMENG CHEN	09/27/2013
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<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>NO. 8, LI-HSIN RD. 6</td> </tr> <tr> <td>Internal Address:</td> <td>SCIENCE-BASED INDUSTRIAL PARK</td> </tr> <tr> <td>City:</td> <td>HSIN-CHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	Street Address:	NO. 8, LI-HSIN RD. 6	Internal Address:	SCIENCE-BASED INDUSTRIAL PARK	City:	HSIN-CHU	State/Country:	TAIWAN	Postal Code:	300-77						
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Application Number:	14056345																		
CORRESPONDENCE DATA																			
Fax Number:	(972)732-9218																		
Phone:	972-732-1001																		
Email:	docketing@slater-matsil.com																		
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>																			
Correspondent Name:	SLATER & MATSIL, L.L.P.																		
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Address Line 4:	DALLAS, TEXAS 75252																		

CH \$40.00 14056345

ATTORNEY DOCKET NUMBER:	TSM13-0754
NAME OF SUBMITTER:	WENDY SAXBY
Signature:	/Wendy Saxby/
Date:	10/17/2013
Total Attachments: 2 source=4351038#page1.tif source=4351038#page2.tif	

ATTORNEY DOCKET NO.
TSM13-0754

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

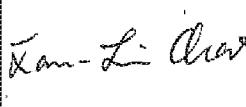
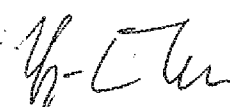
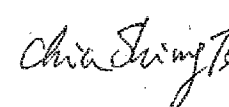
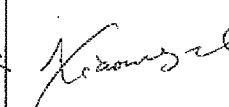
WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	3D Integrated Circuit and Methods of Forming the Same			
SIGNATURE OF INVENTOR AND NAME	 Lan-Lin Chao	 Yeur-Luen Tu	 Chia-Shiung Tsai	 Xiaomeng Chen
DATE	2013.9.27	2013.9.27	2013.9.27	2013.9.27
RESIDENCE	Sindian City, Taiwan	Taichung, Taiwan	Hsin-Chu, Taiwan	Hsin-Chu, Taiwan

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ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and


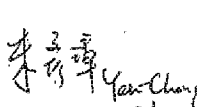
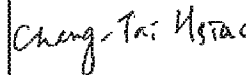
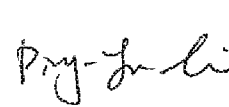
WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year.

TITLE OF INVENTION	3D Integrated Circuit and Methods of Forming the Same			
SIGNATURE OF INVENTOR AND NAME	 Hsun-Chung Kuang	 Yen-Chang Chu	 Cheng-Tai Hsiao	 Ping-Yin Liu
DATE	2013.9.27	2013.10.03	2013.9.27	2013.9.27
RESIDENCE	Hsin-Chu, Taiwan	Tainan City, Taiwan	Tainan City, Taiwan	Yonghe City, Taiwan

TSM13-0754

Page 1 of 2

Assignment